



Material Content Data Sheet



Sales Product Name		BAW 56 E6327		Issued		29. August 2013		
MA#		MA000432718						
Package		PG-SOT23-3-16		Weight*		8.82 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	noble metal	gold	7440-57-5	0.002	0.02		229	
	non noble metal	arsenic	7440-38-2	0.000	0.00		2	
	inorganic material	silicon	7440-21-3	0.035	0.39	0.41	3913	4144
leadframe	non noble metal	chromium	7440-47-3	0.008	0.09		933	
	inorganic material	silicon	7440-21-3	0.001	0.01		62	
	non noble metal	titanium	7440-32-6	0.003	0.03		311	
wire	non noble metal	copper	7440-50-8	2.731	30.96	31.09	309584	310890
	noble metal	gold	7440-57-5	0.012	0.14	0.14	1407	1407
	encapsulation	organic material	carbon black	1333-86-4	0.058	0.66		6553
plastics		brominated resin	-	0.087	0.98		9829	
inorganic material		antimonytrioxide	1309-64-4	0.116	1.31		13106	
plastics		epoxy resin	-	1.243	14.09		140890	
leadfinish	inorganic material	silicondioxide	60676-86-0	4.277	48.49	65.53	484921	655299
	non noble metal	tin	7440-31-5	0.150	1.70	1.70	16965	16965
plating	noble metal	silver	7440-22-4	0.100	1.13	1.13	11295	11295
*deviation	< 10%		Sum in total:			100,00		1000000

Important Remarks:

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